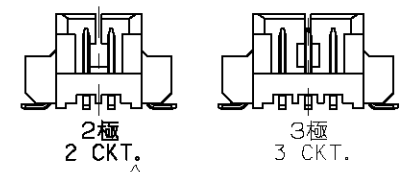


注記 NOTES

1. 嵌合相手 : 51021 シリーズ MATE WITH : 51021 SERIES
- △ 水平面上においての、ウエハー底面 **W** とソルダーテール及びフィッティングネイル底面とのズレ量を示す。
MISALIGNMENT OF SOLDER TAIL & FITTING NAIL FROM **W**
- △ 偶数極にのみ適用。APPLY EVEN CIRCUIT PRODUCTS.
- △ ロック窓は、2、3極は1ヶ所、4極以上は2ヶ所とする。
LOCKING WINDOW : ONE PLACE FOR 2&3 CKTS.
TWO PLACES FOR MORE THAN 4 CKTS.
5. 材質 MATERIAL PA, UL94V-0 COLOR:NATURAL
ウエハー : WAFER
ピン : リン青銅
PIN : PHOS-BRO
錫メッキ 1.0マイクロメートル以上
: MATTE TIN 1.0 MICROMETER MINIMUM
ニッケル下地 1.0マイクロメートル以上
: NICKEL(Under PLATING)1.0 MICROMETER MINIMUM
金具 : リン青銅
FITTING NAIL : PHOS-BRO
錫メッキ 1.0マイクロメートル以上
: MATTE TIN 1.0 MICROMETER MINIMUM
ニッケル下地 1.0マイクロメートル以上
: NICKEL(Under PLATING)1.0 MICROMETER MINIMUM
6. 本製品は 53398-***10 の鉛フリー品である。
THIS PRODUCT IS LEAD FREE OF 53398-***10.



△ ロック形状図
LOCK CONFIGURATION

REVISED EC NO: J2010-0213 DRWN:TKON CHKD:NUKITA APPR:NUKITA 2009/09/25 2009/09/25 2009/09/28	DESCRIPTION GENERAL TOLERANCES (UNLESS SPECIFIED) 10 UNDER ±0.2 10 OVER 30 UNDER ±0.25 30 OVER ±0.3 ANGULAR ±3 ° DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	DIMENSION STYLE MM ONLY		SCALE ---	53398-***19 MODEL NO.	
		DRAWN BY MNINOMIYA	DATE 04/02/06	TITLE 1.25 W/B CONN. ASS'Y FOR SMT(ST.) -LEAD FREE-	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
		CHECKED BY KTOJO	DATE 04/02/06	APPROVED BY MSASAO	DATE 04/02/06	MOLEX MOLEX INCORPORATED
		MATERIAL NO. SEE SHEET 2	DOCUMENT NO. SD-53398-032	SHEET NO. 1 OF 2		
		SIZE A3				THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION

10 9 8 7 6 5 4 3 2 1

F

F

E

E

D

D

C

C

B

B

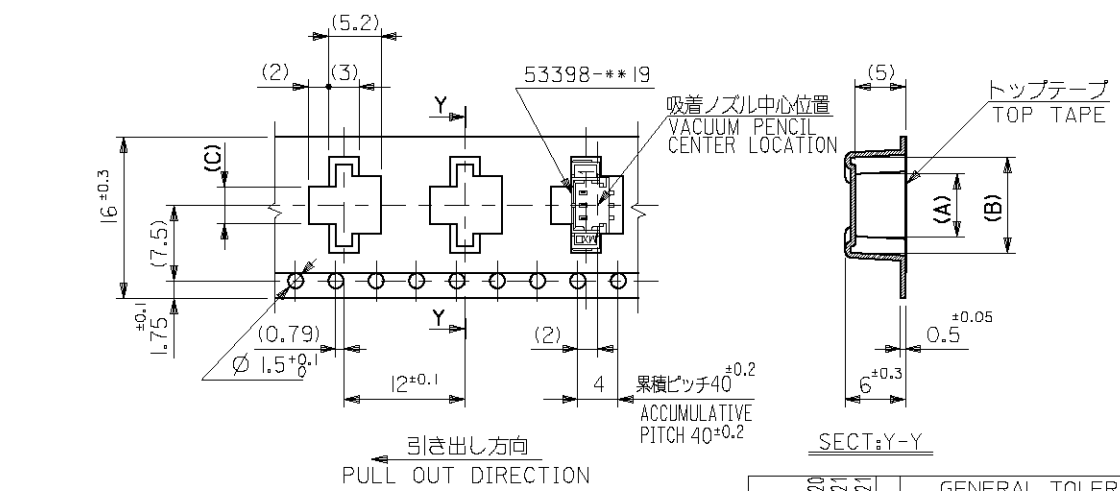
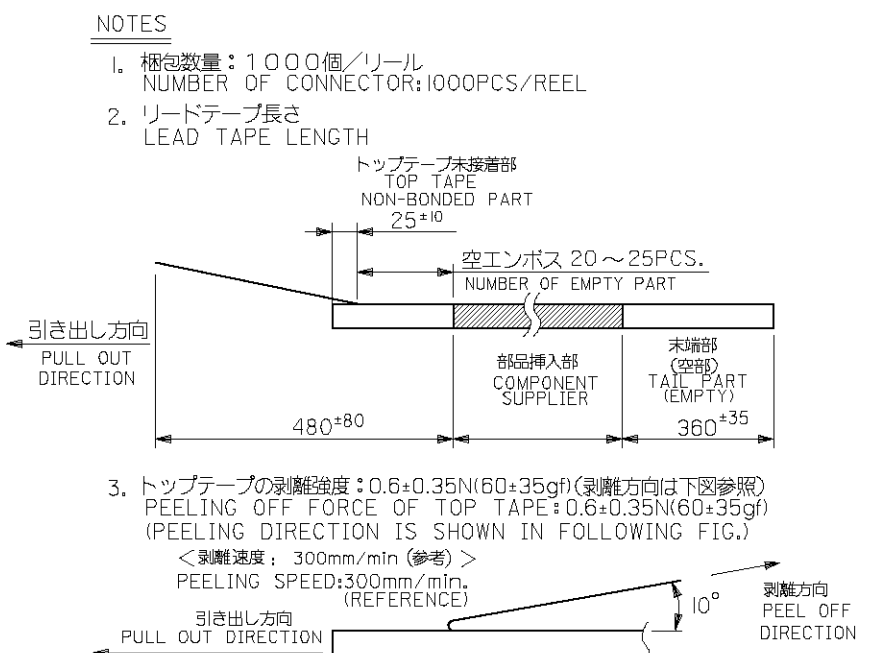
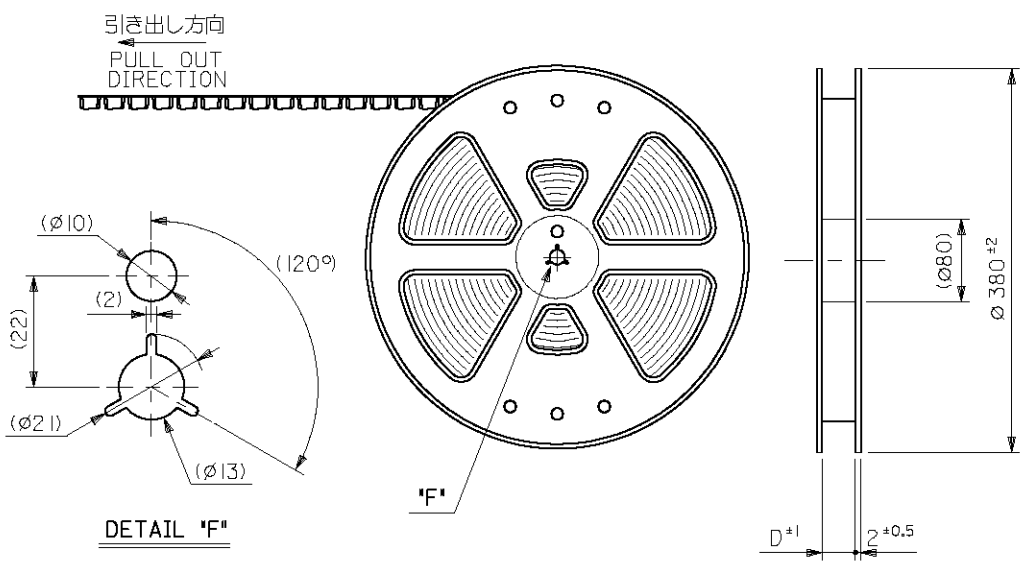
A

A

23.9	23.5	20.5	18.6	19.3	17.5	53398-1571	15
22.65	22.25	19.25	17.35	18.05	16.25	53398-1471	14
21.4	21	18	16.1	16.8	15	53398-1371	13
20.15	19.75	16.75	14.85	15.55	13.75	53398-1271	12
18.9	18.5	15.5	13.6	14.3	12.5	53398-1171	11
17.65	17.25	14.25	12.35	13.05	11.25	53398-1071	10
16.4	16	13	11.1	11.8	10	53398-0971	9
15.15	14.75	11.75	9.85	10.55	8.75	53398-0871	8
13.9	13.5	10.5	8.6	9.3	7.5	53398-0771	7
12.65	12.25	9.25	7.35	8.05	6.25	53398-0671	6
11.4	11	8	6.1	6.8	5	53398-0571	5
10.15	9.75	6.75	4.85	5.55	3.75	53398-0471	4
8.9	8.5	5.5	3.6	4.3	2.5	53398-0371	3
7.65	7.25	4.25	2.35	3.05	1.25	53398-0271	2
F	E	D	C	B	A	EMBOSSED TAPE PKG. (HIGH BARRIER PKG.) ORDER No.	種数 No. of crt's.

CONNECTOR SERIES NO. 53398-**-19

REVISED EC NO: J2010-0213 DRWN:TKON 2009/09/25 CHKD:NUKITA 2009/09/25 APPR:NUKITA 2009/09/28	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY	SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
	10 UNDER	±0.2	DRAWN BY MNINOMIYA	DATE 04/02/06	TITLE 1.25 W/B CONN. ASS'Y FOR SMT(ST.) -LEAD FREE-		
	10 OVER 30 UNDER	±0.25	CHECKED BY KTOJO	DATE 04/02/06	MOLEX INCORPORATED		
	30 OVER	±0.3	APPROVED BY MSASAO	DATE 04/02/06			
ANGULAR ±3 °		MATERIAL NO. SEE TABLE	DOCUMENT NO. SD-53398-032	SHEET NO. 2 OF 2			
	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	SIZE A3	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION				



REVISED	EC NO: J2009-2060	2009/05/20	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
	DRWN:TKN	2009/05/21	10 UNDER	±0.2	DRAWN BY	DATE	TITLE	1.25 W/B CONN WAFER ASSY FOR SMT. EMBSTP. PKG. -LEAD FREE-		
CHKD:HMATSUMOTO	2009/05/21	10 OVER 30 UNDER	±0.25	CHECKED BY	DATE	MOLEX INCORPORATED				
APPR:NUKITA	2009/05/21	30 OVER	±0.3	APPROVED BY	DATE	SEE TABLE & SHEET 2.3		SD-53398-033	1 OF 3	
REV	DESCRIPTION	ANGULAR	±3 °	MATERIAL NO.	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION					
			DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS							

- 53398-**-19 の詳細寸法については図面 SD-53398-032 を参照下さい。
RE DETAILED DIMENSIONS,SEE SD-53398-032.
- 材料 (MATERIAL)
キャリアテープ (CARRIER TAPE):ポリプロピレン (POLYPROPYLENE)
トップテープ (TOP TAPE): PET ,PE ,PEF
リール (REEL):ポリスチレン (P S) <リサイクル材含む>
POLYSTYREN(PS) <RECYCLE MATERIAL CONTAINED>
- 本製品は 53398-**-90 の鉛フリー品である。
THIS PRODUCT IS LEAD FREE OF 53398-**-90.
- 本製品は乾燥剤入り、ハイバリア梱包仕様である。
THIS PRODUCT IS HIGH BARRIER PACKAGE WITH DESICCANT.

F

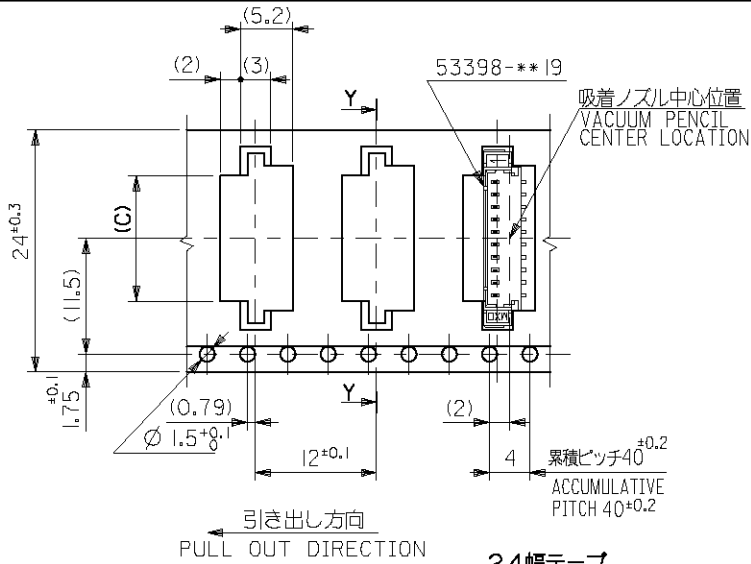
E

D

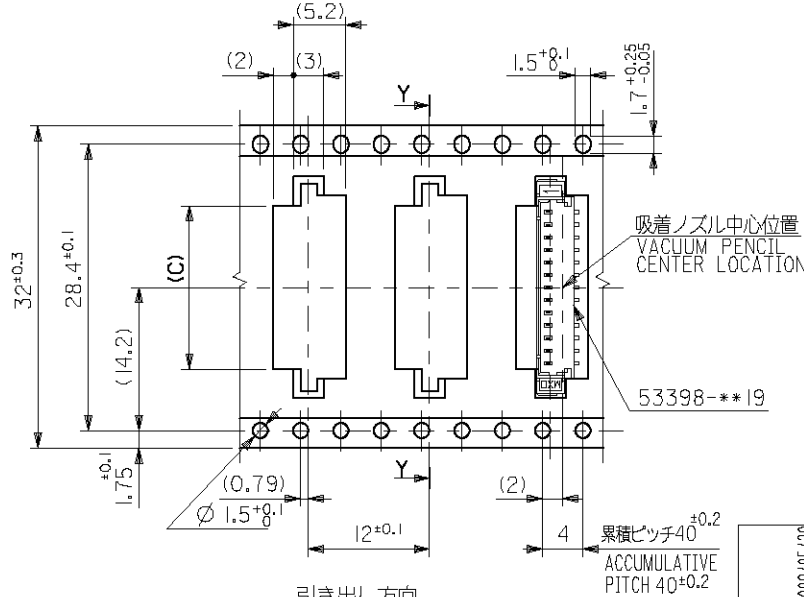
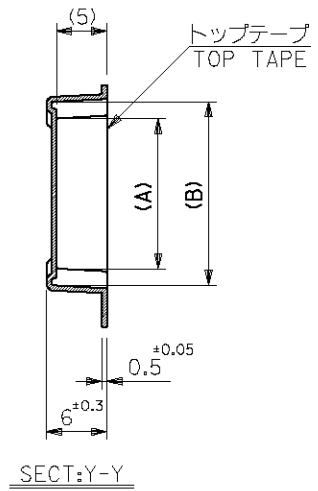
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B

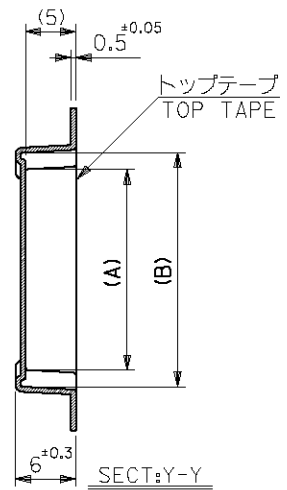
A



24幅テープ (TAPE WIDTH:24)

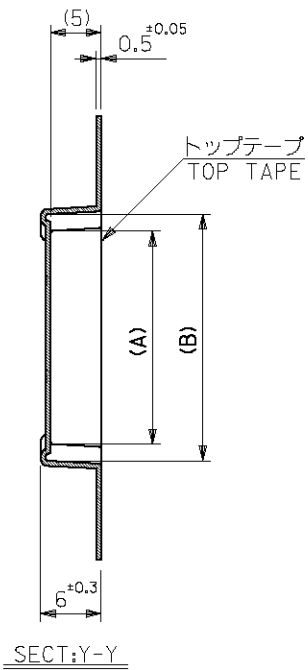
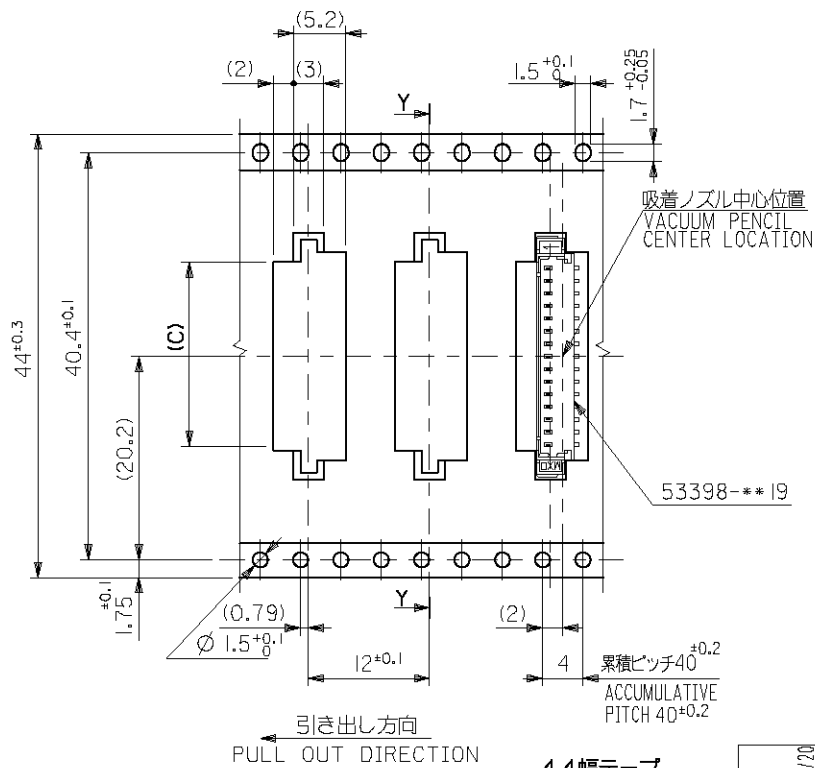


32幅テープ (TAPE WIDTH:32)



32	37.4	33.4	16.2	22	18.3	53398-1371	13	
			14.95	20.75	17.05	▲ -1271	12	
24	29.4	25.4	13.7	19.5	15.8	▲ -1171	11	
			12.45	18.25	14.55	-1071	10	
			11.2	17	13.3	-0971	9	
			9.95	15.75	12.05	-0871	8	
			8.7	14.5	10.8	-0771	7	
			7.45	13.25	9.55	-0671	6	
24	29.4	25.4	6.2	12	8.3	▼ -0571	5	
			4.95	10.75	7.05	53398-0471	4	
キャリアテープ幅 CARRIER TAPE WIDTH		E	D	(C)	(B)	(A)	MATERIAL NO.	極致 CKT.

REVISED EC NO: J2009-2060 DRWN:TKN 2009/05/20 CHKD:HMATSUMOTO 2009/05/21 APPR:NUKITA 2009/05/21	DESCRIPTION	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
		10 UNDER	±0.2	DRAWN BY NINOMIYA	DATE '04/02/06	TITLE 1.25 W/B CONN WAFER ASSY FOR SMT. EMBSTP. PKG. -LEAD FREE-			
		10 OVER 30 UNDER	±0.25	CHECKED BY K.TOJO	DATE '04/02/06	APPROVED BY M.SASAO '04/02/06			
		30 OVER	±0.3	MATERIAL NO. SEE TABLE & SHEET 1.3		DOCUMENT NO. SD-53398-033		SHEET NO. 2 OF 3	
ANGULAR ±3 °		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		MATERIAL NO. SEE TABLE & SHEET 1.3					
SIZE A3		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION							



引き出し方向
PULL OUT DIRECTION

44幅テープ
(TAPE WIDTH:44)

REVISED	EC NO: J2009-2060	2009/05/20
	DRWN:TKON	2009/05/21
	CHKD:HMATSUMOTO	2009/05/21
	APPR:NUKITA	2009/05/21
REV	DESCRIPTION	

GENERAL TOLERANCES (UNLESS SPECIFIED)	
10 UNDER	±0.2
10 OVER 30 UNDER	±0.25
30 OVER	±0.3
ANGULAR	±3 °
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	

44	49.4	45.4	18.7	24.5	20.8	53398-1571	15
キャリアテープ幅 CARRIER TAPE WIDTH	E	D	(C)	(B)	(A)	MATERIAL NO.	極数 CKT.
			17.45	23.25	19.55	53398-1471	14

DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
DRAWN BY NINOMIYA	DATE '04/02/06	TITLE 1.25 W/B CONN WAFER ASSY FOR SMT. EMBSTP. PKG. -LEAD FREE-		
CHECKED BY K.TOJO	DATE '04/02/06	MOLEX INCORPORATED		
APPROVED BY M.SASAO	DATE '04/02/06	DOCUMENT NO. SD-53398-033	SHEET NO. 3 OF 3	
THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION				